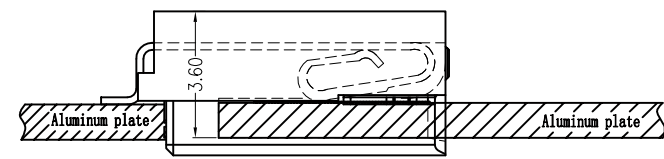
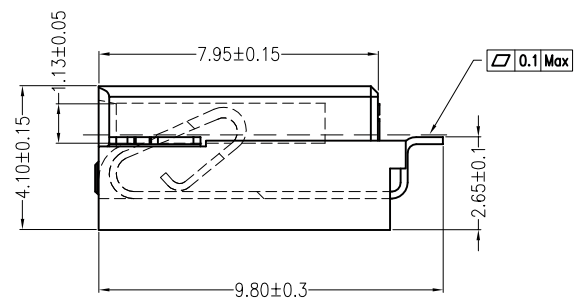
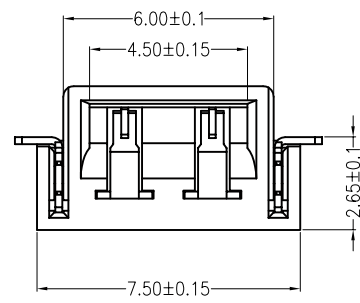
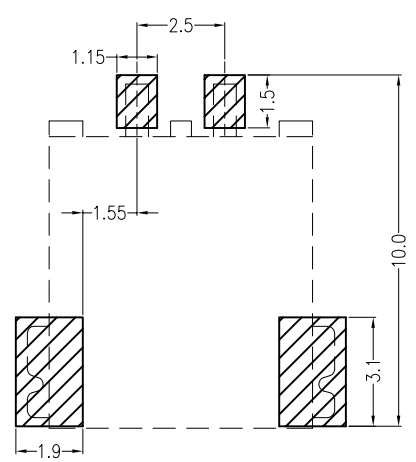
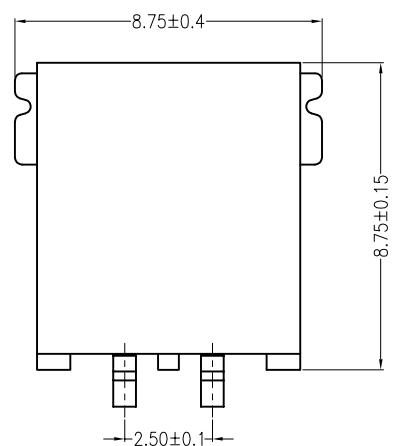


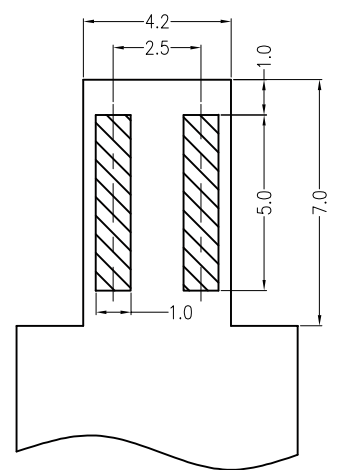
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2017.03.23



Assembly Layout



Board Layout



Mating Aluminum plate detail

主要技术参数 Main Specifications

- 板 厚 (thickness): 1.0mm
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 250V AC DC
- 额定电流 (Rated current): 2.0A AC DC
- 耐 电 压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range): $-40^{\circ}C \sim +120^{\circ}C$



C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
LEDsconn				TITLE: - 2.5mmPITCH 90°WAFER SMT TYPE
X.±0.5	X.±5'	USE:	CUSTOMER	
.X±0.3	.X±2'	APPD:		
.XX±0.25	.XX±1'	CHKD:	DWG NO.:	
--	--	DR:	SCALE	
⊕	☐	UNITS: mm	吴丹平	SHEET
			1 : 1	1 / 1